



PARA LIGHT ELECTRONICS CO., LTD.

11F., No. 8, Jiankang Rd., Zhonghe Dist., New Taipei City 235, Taiwan,
Tel: 886-2-2225-3733 Fax: 886-2-2225-4800
E-mail: para@para.com.tw <http://www.para.com.tw>

DATA SHEET

PART NO.: L-C192JYCT

REV: A/1

CUSTOMER'S APPROVAL : _____

DCC : _____

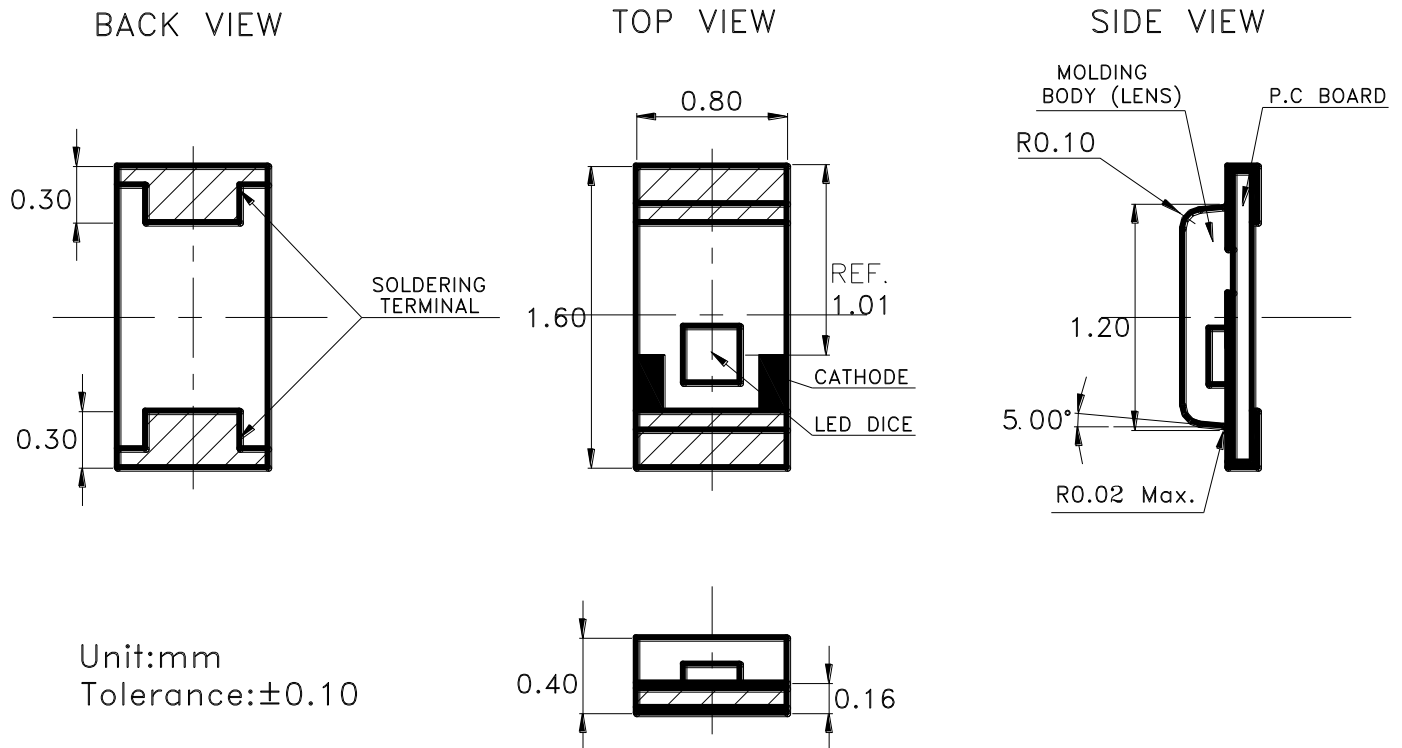
DRAWING NO. : DS-75-21-0002G

DATE : 2021-11-13

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● PACKAGE OUTLINE DIMENSIONS



Notes:

1. All dimensions are in millimeters.
2. Tolerance is $\pm 0.1\text{mm}$ (.004") unless otherwise noted.

● Features

- * Top view, wide view angle, single color Chip LED.
- * Package in 8mm tape on 7" diameter reels.
- * Compatible with automatic Pick & Place equipment.
- * Compatible with Infrared and Wave soldering reflow solder processes.
- * EIA STD package.
- * I.C. compatible.
- * Pb free product.
- * Meet RoHS Green Product.
- * Moisture sensitivity level: 3



SURFACE MOUNT DEVICE LED

Part No. : L-C192JYCT

REV: A/1

● CHIP MATERIALS

- * Dice Material : AlInGaP
- * Light Color : Yellow
- * Lens Color : Water Clear

● Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rating	Unit
PD	Power Dissipation	75	mW
IPF	Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	80	mA
IF	Continuous Forward Current	30	mA
VR	Reverse Voltage	5	V
Topr	Operating Temperature Range	-40 ~ +85	°C
Tstg	Storage Temperature Range	-40 ~ +85	°C

● Electro-Optical Characteristics(Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	IV	40	80	180	mcd	IF=20mA
Viewing Angle	2θ 1/2		130		deg	Note 2
Peak Emission Wavelength	λ p		592		nm	Measurement @Peak
Dominant Wavelength	λ d	587	590	597	nm	IF=20mA
Spectral Line Half-Width	Δ λ		20		nm	
Forward Voltage	VF	1.9	2.05	2.4	V	IF =20mA
Reverse Current	IR			10	μ A	VR = 5V



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● Bin Code List

Luminous Intensity(IV), Unit:mcd@20mA		
Bin Code	Min	Max
R1	40	60
R2	60	90
S1	90	130
S2	130	180

Tolerance of each bin are $\pm 15\%$

Forward Voltage(VF), Unit:V@20mA		
Bin Code	Min	Max
4	1.9	2.0
5	2.0	2.1
6	2.1	2.2
7	2.2	2.3
8	2.3	2.4

Tolerance of each bin are ± 0.1 Volt

Dominant Wavelength (Hue),Unit: nm@20mA		
Bin Code	Min	Max
YA01	587.0	589.0
YA02	589.0	591.0
YB01	591.0	593.0
YB02	593.0	595.0
YC01	595.0	597.0

Tolerance of each bin are ± 0.5 nm

Notes:

1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
3. Caution in ESD :
Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

● Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

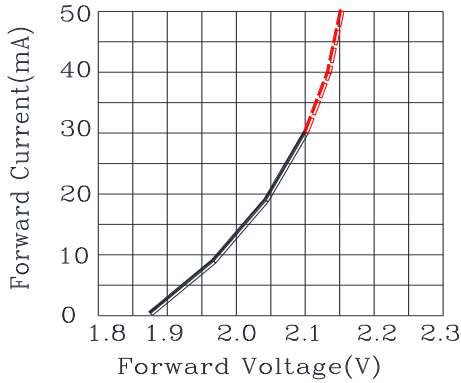


Fig.2 Forward Current vs.Forward Voltage

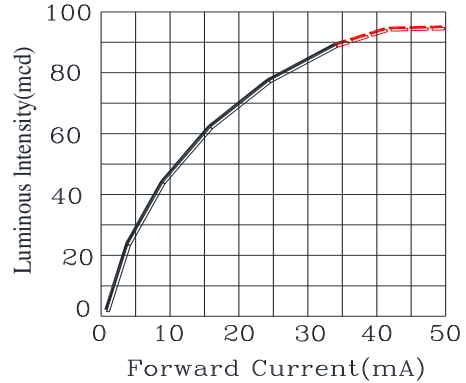


Fig.3 Luminous Intensity vs.Forward Current

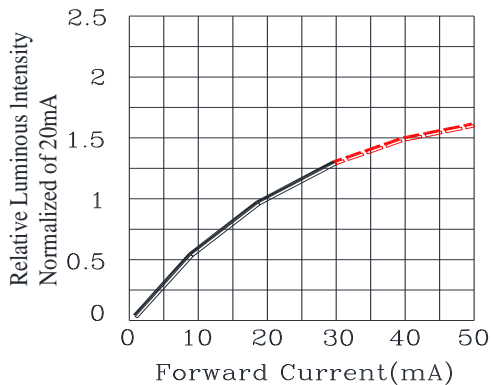


Fig.4 Relative Luminous Intensity vs.Forward Current

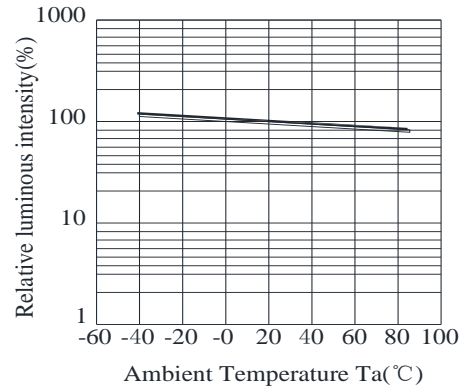


Fig.5 Luminous Intensity vs.Ambient Temperature

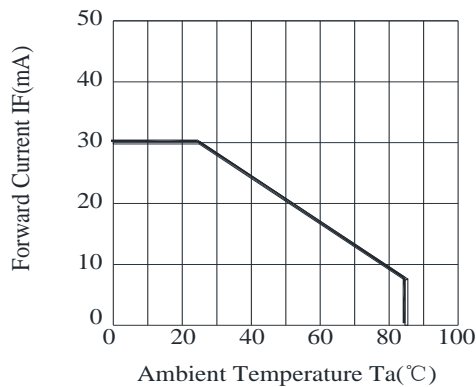


Fig.6 Forward Current Derating Curve

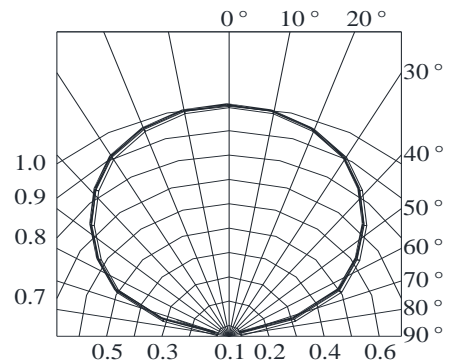


Fig.7 Relative Intensity vs.Angle



SURFACE MOUNT DEVICE LED

Part No. : L-C192JYCT

REV: A/1

● Label Explanation



ITEM CODE:PARRA LIGHT

PART NO: L-C192JYCT

IV --- Luminous Intensity Code

LOT NO: EM S L 12 09 0110
 A B C D E F

A---EM: Emos Code

B---S:SMD

L---Local

D---Year

E---Month

F---SPEC.

PACKING QUANTITY OF BAG :

3000pcs for 150、170、110、155、115 series

4000pcs for 191 series

5000pcs for 192 series

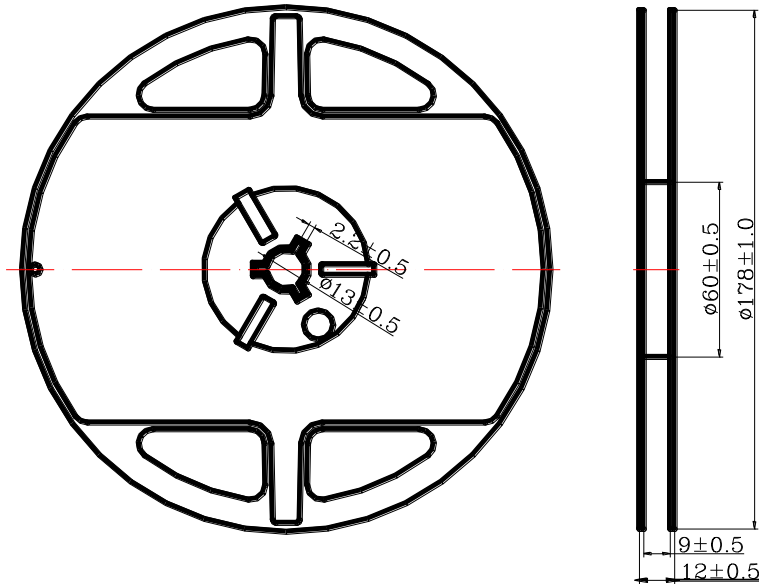
DATE CODE: 2012 09 10
 G H I

G--- Year

H--- Month

I --- Day

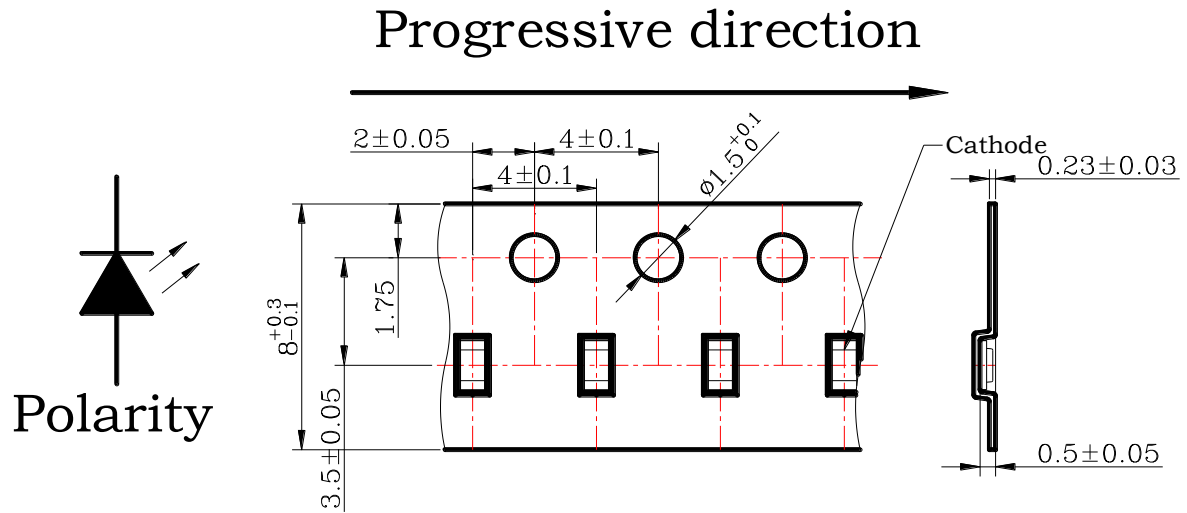
● Reel Dimensions



Notes:

1. Taping Quantity : 5000pcs
2. The tolerances unless mentioned is $\pm 0.1\text{mm}$, Angle $\pm 0.5^\circ$, Unit : mm.

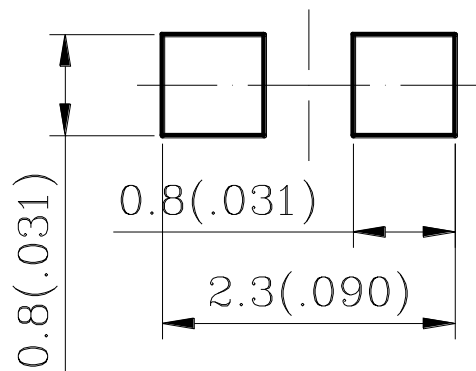
● Package Dimensions Of Tape And Reel



Notes: All dimensions are in millimeters.

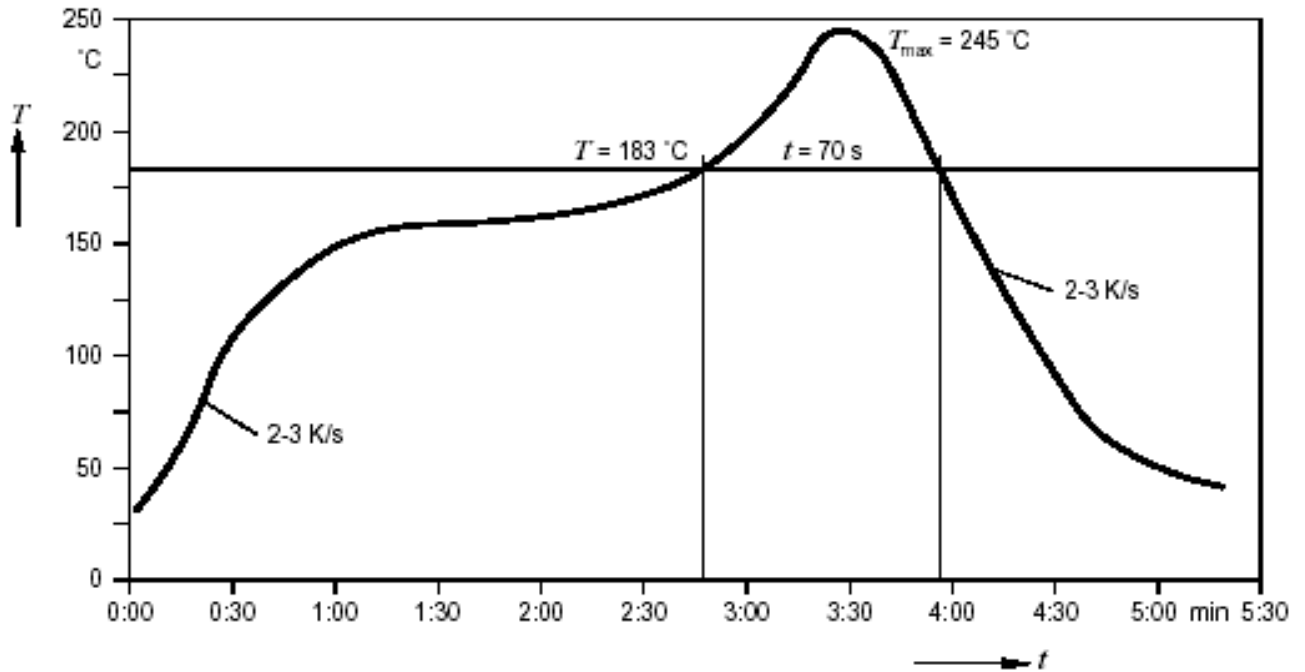
● Cleaning

- * If cleaning is required , use the following solutions for less than 1 minute and less than 40°C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- * Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

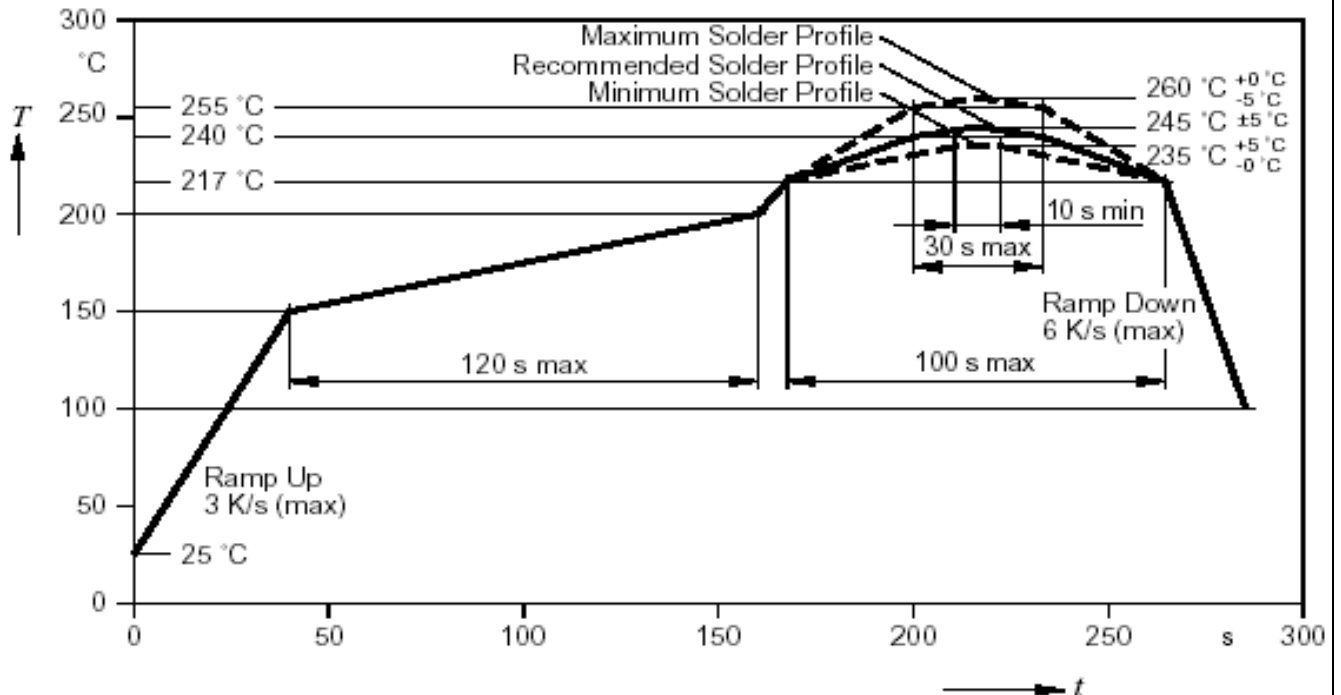
● Suggest Soldering Pad Dimensions

Direction of PWB camber
and go to reflow furnace

● Suggest Sn/Pb IR Reflow Soldering Profile Condition:



● Suggest Pb-Free IR Reflow Soldering Profile Condition:





SURFACE MOUNT DEVICE LED

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● CAUTIONS

1.Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application). Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage :

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5°C for 24 hours.

3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition.

Reflow Soldering :

Pre-heat 120~150 °C, 120sec. MAX., Peak temperature : 240 °C Max. Soldering time : 10 sec Max.

Soldering Iron : (Not recommended)

Temperature 300 °C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

Wave soldering :

Pre-heat 100 °C Max, Pre-heat time 60 sec. Max, Solder wave 260 °C Max, Soldering time 5 sec. Max. performed consecutively cooling process is required between 1st and 2nd soldering processes.

4. Lead-Free Soldering

For Reflow Soldering :

- 1、 Pre-Heat Temp: 150-180°C,120sec.Max.
- 2、 Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3、 Peak Temperature: 260°C , 5sec.
- 4、 Reflow Repetition: 2 Times Max.
- 5、 Suggest Solder Paste Formula : 93.3 Sn/3.1 Ag/3.1 Bi/0.5 Cu

For Soldering Iron (Not Recommended) :

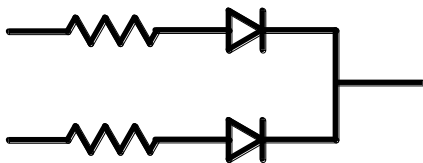
- 1、 Iron Tip Temp: 350°C Max.
- 2、 Soldering Iron: 30w Max.
- 3、 Soldering Time: 3 Sec. Max. One Time.

For Dip Soldering :

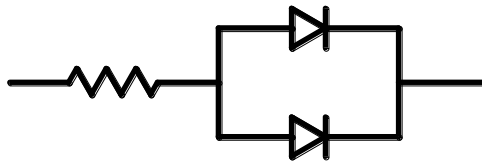
- 1、 Pre-Heat Temp: 150°C Max. 120 Sec. Max.
- 2、 Bath Temp: 265°C Max.
- 3、 Dip Time: 5 Sec. Max.

5. Drive Method

Circuit model A



Circuit model B



(A)Recommended circuit.

(B)The difference of brightness between LED`s could be found due to the Vf-If characteristics of LED.